

Appl. No. : 09/389,720  
Filed : September 3, 1999

#### REMARKS

This is responsive to the Examiner's Office Action mailed August 1, 2002. Applicant has hereby amended Claim 20 and cancelled Claim 27. Thus, Claims 20-24, 26, 29 and 30 are pending in this application.

The specific changes to the amended claim are shown on a separate page attached hereto and entitled **VERSION WITH MARKINGS TO SHOW CHANGES MADE**, which follows the signature page of this Response. On this page, any insertions are underlined while any [deletions are in brackets].

A clean copy of the pending claims is attached hereto on a separate page and entitled **CLEAN COPY OF PENDING CLAIMS**, which also follows the signature page of this Response.

#### **SPECIFICATION**

The Examiner objected to the disclosure and stated that there appeared to be a typographical error in the word "polymide" in Claim 26.

Applicant has noted that in the art different spellings are used for "polymide," for example, "polyimide." Thus, the skilled artisan would recognize that the word "polymide" encompasses all these spelling variations and modifications. Accordingly, no correction is believed necessary.

#### **CLAIMS**

The Examiner rejected Claims 20-23, 26, 27, 29 and 30 under 35 U.S.C. § 102(b) as being anticipated by Marutsuka (JP 58-178544) and Claims 20-24, 27, 29 and 30 under 35 U.S.C. § 102(b) as being anticipated by Nakashima et al. (U.S. Pat. No. 5,661,086).

Applicant respectfully traverses these rejections and the Examiner's characterization of the cited references. In this case, Applicant has amended Claim 20 and cancelled Claim 27 to more particularly define embodiments of the invention.

Independent Claim 20 is directed to an assembly and recites, among other things, that each one of the substrate units includes a substantially central cavity adapted to receive wires from a corresponding die which connect to a first surface of the film and that the dies are attachable to a second surface of the film with the second surface being opposed to the first surface. Claim 20 also recites a carrier in mechanical communication with the first surface of the film. None of the cited references disclose, teach or suggest an assembly as set forth in Applicant's Claim 20. Thus, it is believed that Claim 20 is patentably distinguished over the cited references. Claims 21-24, 26, 29 and 30 depend

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from Claim 20. Therefore, Applicant submits that Claims 20-24, 26, 29 and 30 are in condition for allowance.

**INFORMATION DISCLOSURE STATEMENT**

Applicant is submitting herewith a Supplemental Information Disclosure Statement. The Examiner's consideration of this Information Disclosure Statement is respectfully requested.

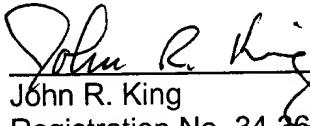
**CONCLUSION**

In view of the forgoing, the present application is believed to be in condition for allowance, and such allowance is respectfully requested. If further issues remain to be resolved, the Examiner is cordially invited to contact the undersigned such that any remaining issues may be promptly resolved. Also, please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Respectfully submitted,

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Dated: November 1, 2002

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**VERSION WITH MARKING TO SHOW CHANGES MADE**

**IN THE CLAIMS:**

Claim 20 has been amended as follows:

20. (THRICE AMENDED) An assembly, comprising:

a film including a plurality of substrate units with [each of] said plurality of substrate units being adapted to electrically interface with a [corresponding]plurality of dies, [each one of said plurality of substrate units being generally defined on said film between a pair of flanking slots wherein each flanking slot in the film extends such that it is in contact with a side rail of a carrier and that said slot is placed only in the area where the assembly is to be cut,]each one of said substrate units including a substantially central cavity adapted to receive wires from a corresponding die which connect to a first surface of said film, said dies being attachable to a second surface of said film with said second surface being opposed to said first surface; and

[that said]a carrier [is] in mechanical communication with said first surface of said film for providing enhanced rigidity to said film by being sized and configured to add material at selected regions of said film.

Claim 27 has been cancelled.